

S/N 09/845,881



**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Quat T. Vu et al.

Examiner: Lourdes C. Cruz

Serial No.: 09/845,881

Group Art Unit: 2827

Filed: April 30, 2001

Docket: 884.384US1

Title: MICROELECTRONIC DEVICE HAVING SIGNAL DISTRIBUTION  
FUNCTIONALITY ON AN INTERFACIAL LAYER THEREOF

**AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111**

Commissioner for Patents  
Washington, D.C. 20231

Applicant has reviewed the Office Action mailed on July 2, 2002. Please amend the above-identified patent application as follows.

*This response is accompanied by a Petition, as well as the appropriate fee, to obtain a three-month extension of the period for responding to the Office action, thereby moving the deadline for response from October 2, 2002 to January 2, 2003.*

**IN THE CLAIMS**

Please substitute the claim set in the appendix entitled Clean Version of Pending Claims for the previously pending claim set. The substitute claim set is intended to reflect amendment of previously pending claims 4, 5, 11, 13, 15, 20, and 26. The specific amendments to individual claims are detailed in the following marked up set of claims.

1. A microelectronic device comprising:
  - a microelectronic die having a plurality of bond pads on an active surface thereof, said microelectronic die being fixed within an opening in a package core; and
    - an interfacial metal layer deposited over said active surface of said microelectronic die, said interfacial metal layer having at least one conductive element that is conductively coupled to multiple bond pads on said active surface of said microelectronic die to provide signal distribution between points within said microelectronic die.
2. The microelectronic device of claim 1, comprising: